0 8 2002 9/893.036

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Ajit V. Sathe

09/893,036

Filed:

Title:

Serial No.:

June 27, 2001

FLEXIBLE TAPE ELECTRONICS PACKAGING (as amended)

Docket: 884.469US1

Examiner: Quang D. Vu

Group Art Unit: 2811

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

**Commissioner for Patents** Washington, D.C. 20231

Applicant has reviewed the Office Action mailed on July 5, 2002. Please amend the aboveidentified patent application as follows.

## IN THE TITLE

Please amend the title as follows: FLEXIBLE TAPE ELECTRONICS PACKAGING [AND METHODS OF MANUFACTURE]

## **IN THE SPECIFICATION**

Please make the paragraph substitutions indicated in the appendix entitled "Clean Version of Amended Specification Paragraphs". The specific changes incorporated in the substitute paragraphs are shown in the following marked-up versions of the original paragraphs.

The subtitle beginning on page 1, line 5 is amended as follows: Technical Field [of the Invention]

The paragraph beginning on page 1, line 7 is amended as follows:

Embodiments of the [The] present invention relate [relates] generally to electronics packaging[.] and, more particularly [More particularly, the present invention relates] to an electronic package that includes an integrated circuit packaged on a flexible tape substrate, and to manufacturing methods related thereto.

The subtitle beginning on page 1, line 12 is amended as follows:

Background Information [of the Invention]